

LN222RPH

Round Type

φ2.0 mm

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	70	mW
Forward current	I_F	25	mA
Pulse forward current *	I_{FP}	150	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-25 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-30 to +100	$^\circ\text{C}$

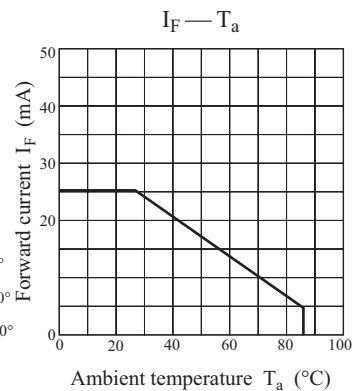
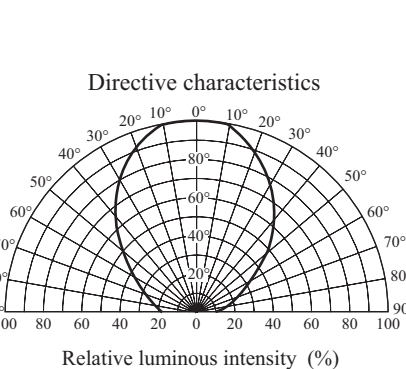
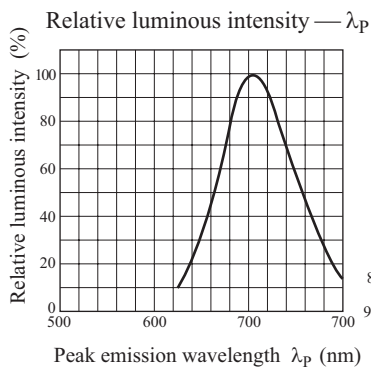
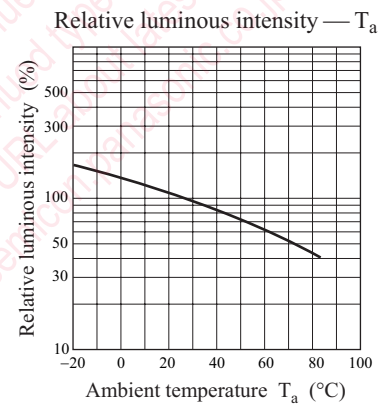
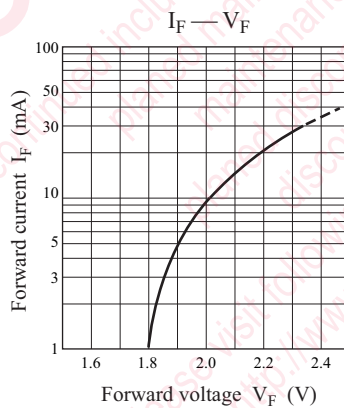
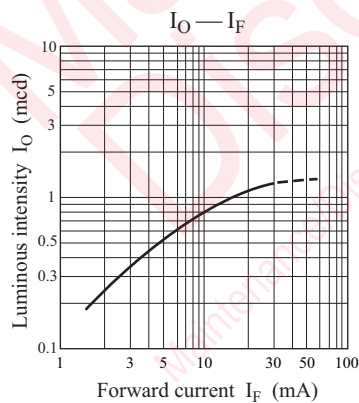
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color

- Red

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		0.4	1.0		mcd
Reverse current	I_R	$V_R = 4\text{ V}$			5	μA
Forward voltage	V_F	$I_F = 20\text{ mA}$		2.2	2.8	V
Peak emission wavelength	λ_p	$I_F = 20\text{ mA}$		700		nm
Spectral half band width	$\Delta\lambda$	$I_F = 20\text{ mA}$		100		nm



Technical drawing of a two-pin connector showing front, side, and top views with dimensions.

- Front View (Left):** Shows the main body with a total length of 27.0 ± 1.0 . The mounting tab has a width of 2.54 and a height of 1.5 . The pin diameter is $\phi 2.1 \pm 0.2$ and the hole diameter is $\phi 2.0 \pm 0.2$. The distance between pins is 2.0 Max. NOT SOLDERED. The overall width is 4.8 ± 0.2 .
- Side View (Middle):** Shows the profile of the connector. Key dimensions include a base thickness of 0.6 , a central section of 0.8 , and a total height of 8.0 ± 0.2 . The pin length is 4.5 ± 0.2 and the distance from the base to the start of the pin is 3.5 .
- Top View (Right):** Shows the top of the connector with a width of 2.4 ± 0.2 and a height of 2.5 ± 0.2 .
- Bottom View (Bottom):** Shows the bottom of the connector with a width of 2.54 and a height of 1.5 .

- Pin name
1: Anode
2: Cathode

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